



## Material Content Data Sheet



<b>Sales Product Name</b>				ESD101-B1-02ELS E6327		<b>Issued</b>		27. September 2017	
<b>MA#</b>				MA001482194					
<b>Package</b>				PG-TSSLP-2-4		<b>Weight*</b>		0.21 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	non noble metal	tin	7440-31-5	0.000	0.17		1669		
	noble metal	gold	7440-57-5	0.001	0.65		6465		
	inorganic material	silicon	7440-21-3	0.010	4.79	5.61	47916	56050	
leadframe	non noble metal	nickel	7440-02-0	0.108	51.68	51.68	516836	516836	
wire	noble metal	gold	7440-57-5	0.003	1.22	1.22	12222	12222	
encapsulation	organic material	carbon black	1333-86-4	0.000	0.19		1889		
	plastics	epoxy resin	-	0.011	5.47		54749		
	inorganic material	silicondioxide	60676-86-0	0.067	32.10	37.76	320953	377591	
leadfinish	noble metal	gold	7440-57-5	0.004	1.76	1.76	17634	17634	
plating	noble metal	gold	7440-57-5	0.004	1.97	1.97	19667	19667	
*deviation	< 10%			Sum in total:		100.00		1000000	

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com